

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

24.04.2026

**WÜRTH
ELEKTRONIK**
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-009my 330x490mm	50201012	9	VS	1	A00 B00
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		2	
B-STD-FR4-ML-0.711mm-035+035-TG150-HF...	50203135	35	L2	3	
		710			
		35	L3		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		4	
A-RS Kupferfolie-009my 330x490mm	50201012	9	RS	5	

Thickness after Pressing

B00:

890 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

990 µm

Dmin:

790 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1000 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

1100 µm

Dmin:

900 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

922 µm

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